Claims:

1. An electroplating chamber leakage plating warning method, comprising:

positioning an electroplated wafer on a fixture at a detection location;

setting a target detection area of the wafer;

operating an image sensor to detect the target detection area of the wafer, and determining whether there is unwanted metal deposition in the target detection area;

if the determination result is that there is unwanted metal deposition in the target detection area of the wafer, indicating that a leakage plating occurs in the electroplating chamber processing that wafer, then an alarm command is issued;

if the determination result is that there is no unwanted metal deposition in the target detection area of the wafer, indicating that no leakage plating occurs in the electroplating chamber processing that wafer, then no alarm command is issued.

2. The method according to claim 1, wherein the fixture at the detection location includes:

a separately set installation fixture; or

a wafer chuck inside a cleaning chamber used for a wafer cleaning process.

3. The method according to claim 1, wherein the step of operating an image sensor to detect the target detection area of the wafer, and determining whether there is unwanted metal deposition in the target detection area further includes:

pre-setting a gray value threshold for the image sensor to issue the alarm command;

the image sensor collects the image of the target detection area of the wafer, generates a target image, and sends the target image to a processor;

the processor receives the target image, performs grayscale processing on the target image, generates gray value data information of the target image, compares the

gray value data information with the preset gray value threshold, and generates a comparison result;

if the comparison result is that the gray value data information is within the gray value threshold, then the result indicates that there is no unwanted metal deposition;

if the comparison result is that the gray value data information exceeds the gray value threshold, then the result indicates that there is unwanted metal deposition.

4. The method according to claim 1, wherein the target detection area of the wafer is set as: a circular ring area extending 1.0-2.0mm from the periphery of the wafer towards the center of the wafer.

5. The method according to claim 1, wherein during the process of the image sensor detecting the target detection area on the wafer, the wafer and the image sensor rotate relative to each other.

6. The method according to claim 5, wherein the relative rotation speed between the wafer and the image sensor is not more than 50 rpm.

7. The method according to claim 1, wherein the image sensor includes a camera for collecting a target image.

8. The method according to claim 1, wherein when the determination result is that a leakage plating occurs in the electroplating chamber, and after issuing the alarm command, the method further includes switching the operational state of the electroplating chamber processing that wafer to a maintenance-required state, prohibiting wafers to be electroplated from entering this electroplating chamber.

9. An electroplating chamber leakage plating warning system, comprising:

a wafer positioning device, used to position an electroplated wafer at a detection location;

a detection device, which uses an image sensor to detect a target detection area of the wafer, wherein the detection device is connected to a processor, and the processor is configured to determine whether there is unwanted metal deposition in the target detection area of the wafer;

an alarm device, used to issue an alarm command when the determination result indicates the presence of unwanted metal deposition in the target detection area of the wafer.